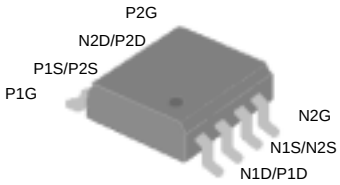
DUAL N- AND DUAL P-CHANNEL ENHANCEMENT-MODE POWER MOSFETS

- Simple drive requirement
- Low on-resistance
- Full-bridge applications, such as
  - LCD monitor inverter



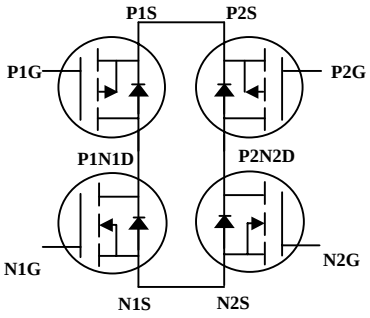
SO-8

N-CH	BV_{DSS}	30V
	$R_{DS(ON)}$	33mΩ
	I_D	6.3A
P-CH	BV_{DSS}	-30V
	$R_{DS(ON)}$	55mΩ
	I_D	-5.1A

Description

Advanced Power MOSFETs from Silicon Standard provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SSM9930M is in the SO-8 package, which is widely preferred for commercial and industrial surface mount applications, and is well suited for applications such as low-voltage inverters and motor drives.



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-channel	P-channel	
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 25	±25	V
I_D @ T_A=25°C	Continuous Drain Current[3]	6.3	-5.1	A
I_D @ T_A=70°C	Continuous Drain Current[3]	4.2	-3.4	A
I_{DM}	Pulsed Drain Current[1]	20	-20	A
P_D @ T_A=25°C	Total Power Dissipation	2.0		W
	Linear Derating Factor	0.016		W/°C
T_{STG}	Storage Temperature Range	-55 to 150		°C
T_J	Operating Junction Temperature Range	-55 to 150		°C

Thermal Data

Symbol	Parameter		Value	Unit
Rthj-amb	Thermal Resistance Junction-ambient[3]	Max.	62.5	°C/W

N-channel Electrical Characteristics @ T_j=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	30	-	-	V
$\Delta BV_{DSS}/\Delta Tj$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I_D=1mA	-	0.037	-	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V, I_D=5A	-	-	33	mΩ
		V_{GS}=4.5V, I_D=3A	-	-	60	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1	-	3	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=5A	-	5.2	-	S
I_{DSS}	Drain-Source Leakage Current (T_j=25°C)	V_{DS}=30V, V_{GS}=0V	-	-	1	uA
	Drain-Source Leakage Current (T_j=70°C)	V_{DS}=24V, V_{GS}=0V	-	-	25	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±25V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=5A	-	7.1	-	nC
Q_{gs}	Gate-Source Charge	V_{DS}=15V	-	2.3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=4.5V	-	3.8	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=15V	-	7.2	-	ns
t_r	Rise Time	I_D=1A	-	10.4	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=6Ω ,V_{GS} =10V	-	18	-	ns
t_f	Fall Time	R_D=15Ω	-	7.8	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	600	-	pF
C_{oss}	Output Capacitance	V_{DS}=25V	-	230	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	94	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=1.7A, V_{GS}=0V	-	-	1.2	V
t_{rr}	Reverse Recovery Time	I_S=1.7A, V_{GS}=0V	-	21.4	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	16	-	nC

P-channel Electrical Characteristics @ T_j=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	-30	-	-	V
$\Delta BV_{DSS}/\Delta Tj$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I_D=-1mA	-	-0.037	-	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=-10V, I_D=-5A	-	-	55	mΩ
		V_{GS}=-4.5V, I_D=-3A	-	-	100	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=-250uA	-1	-	-3	V
g_{fs}	Forward Transconductance	V_{DS}=-10V, I_D=-5A	-	4.8	-	S
I_{DSS}	Drain-Source Leakage Current (T_j=25°C)	V_{DS}=-30V, V_{GS}=0V	-	-	-1	uA
	Drain-Source Leakage Current (T_j=70°C)	V_{DS}=-24V, V_{GS}=0V	-	-	-25	uA
I_{GSS}	Gate-Source Leakage	V_{GS}= ± 25V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=-5A	-	7.3	-	nC
Q_{gs}	Gate-Source Charge	V_{DS}=-15V	-	2.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=-4.5V	-	3.8	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=-15V	-	10.8	-	ns
t_r	Rise Time	I_D=-1A	-	7.6	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=6Ω ,V_{GS} =-10V	-	19.6	-	ns
t_f	Fall Time	R_D=15Ω	-	17.5	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	486	-	pF
C_{oss}	Output Capacitance	V_{DS}=-25V	-	185.5	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	133.8	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=-1.7A, V_{GS}=0V	-	-	-1.2	V
t_{rr}	Reverse Recovery Time	I_S=-1.7A, V_{GS}=0V	-	21	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=-100A/μs	-	15	-	nC

Notes:

1.Pulse width limited by max. junction temperature.

2.Pulse width ≤300us , duty cycle ≤2%.

3.Surface mounted on 1 in^2 copper pad of FR4 board ; 135°C/W when mounted on min. copper pad.

N-channel

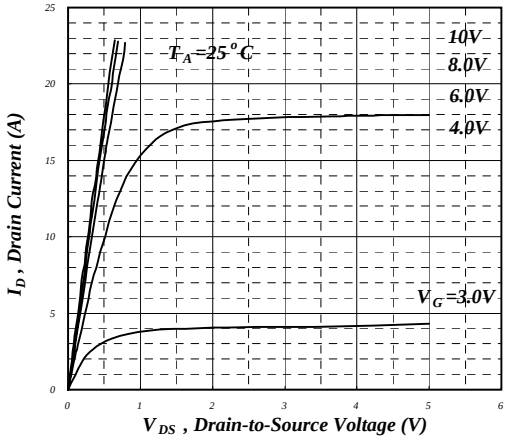


Fig 1. Typical Output Characteristics

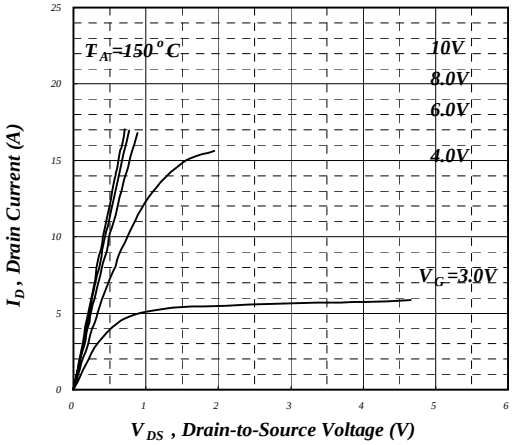


Fig 2. Typical Output Characteristics

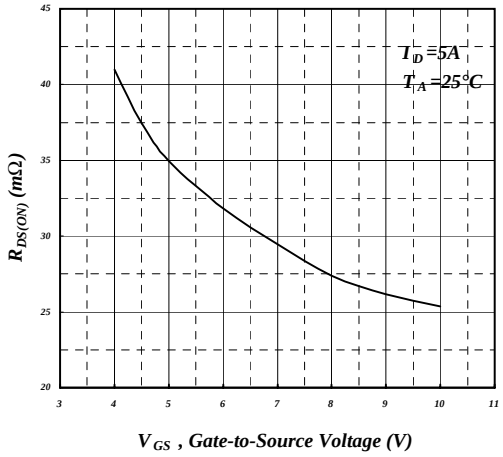


Fig 3. On-Resistance vs. Gate Voltage

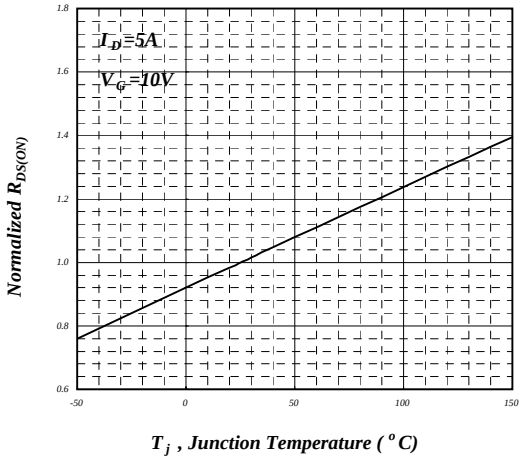


Fig 4. Normalized On-Resistance vs. Junction Temperature

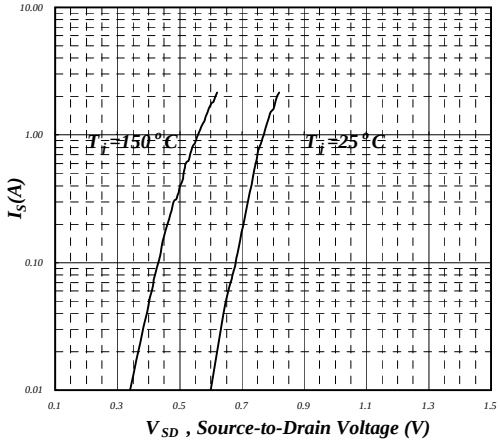


Fig 5. Forward Characteristic of Reverse Diode

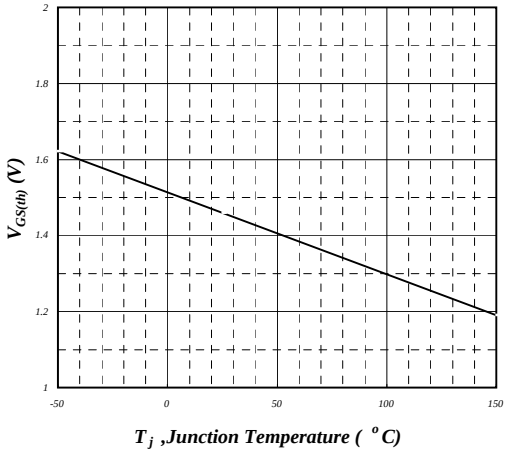


Fig 6. Gate Threshold Voltage vs. Junction Temperature

N-channel

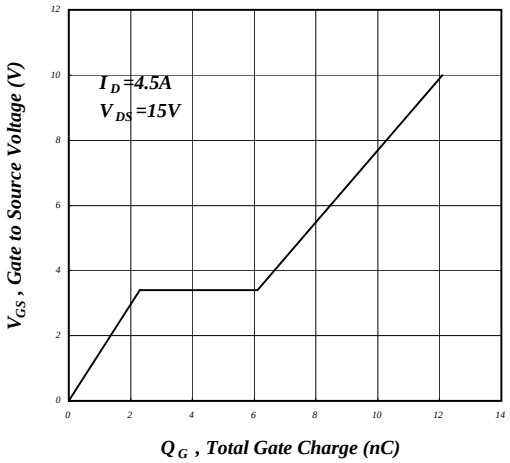


Fig 7. Gate Charge Characteristics

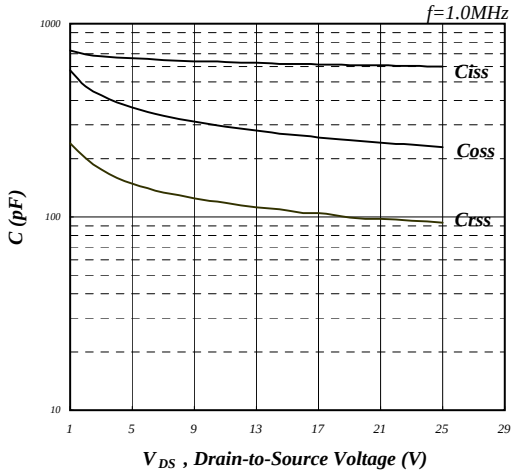


Fig 8. Typical Capacitance Characteristics

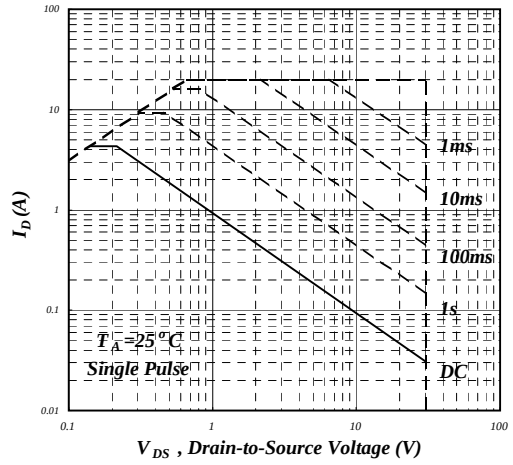


Fig 9. Maximum Safe Operating Area

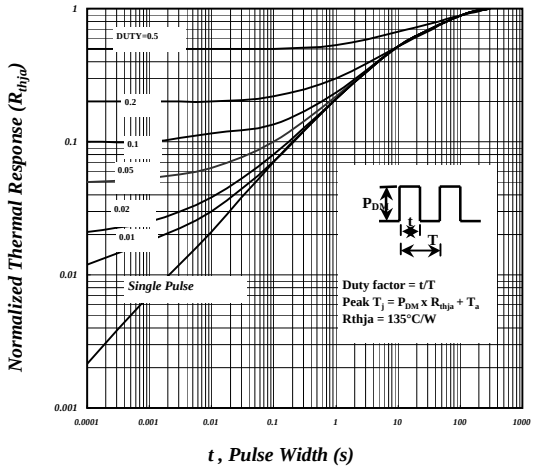


Fig 10. Effective Transient Thermal Impedance

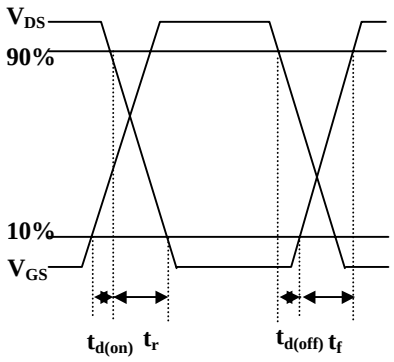


Fig 11. Switching Time Waveform

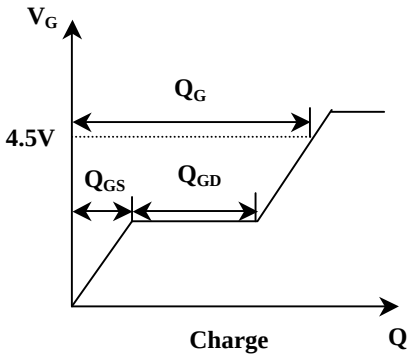
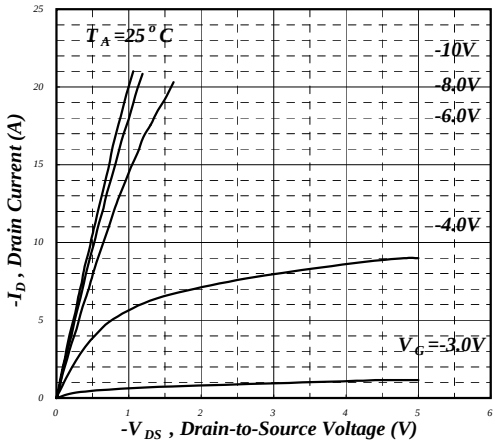


Fig 12. Gate Charge Waveform

P-channel



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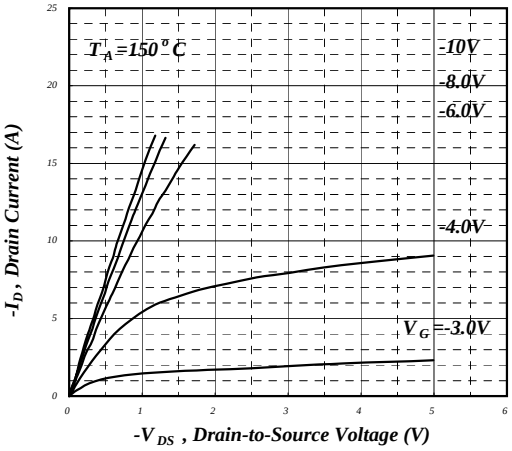


Fig 2. Typical Output Characteristics

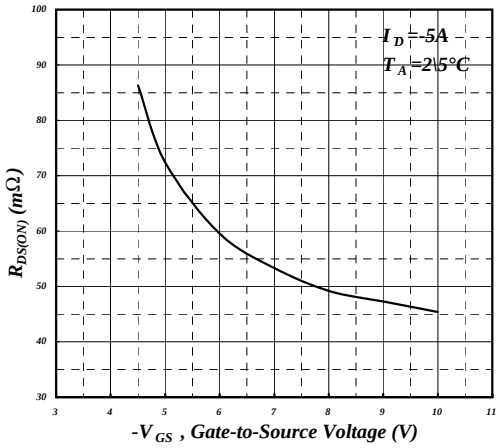


Fig 3. On-Resistance vs. Gate Voltage

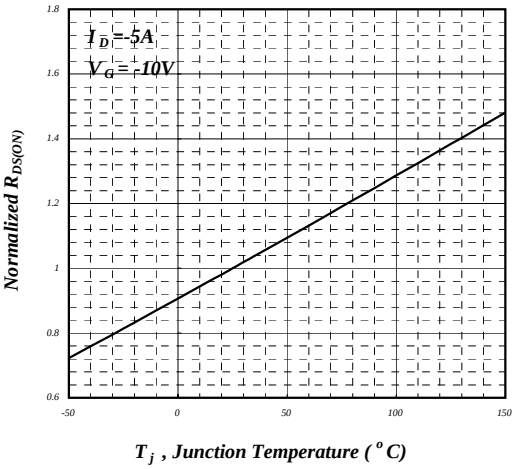
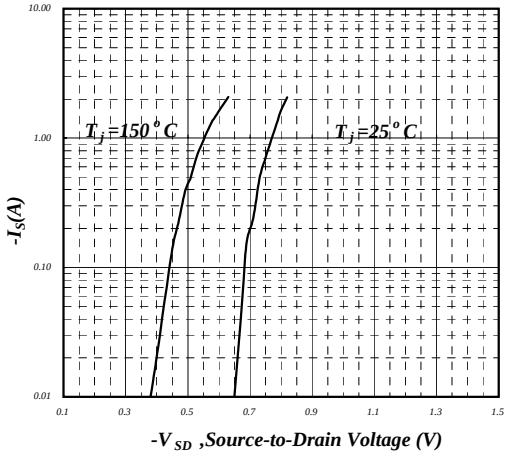


Fig 4. Normalized On-Resistance vs. Junction Temperature



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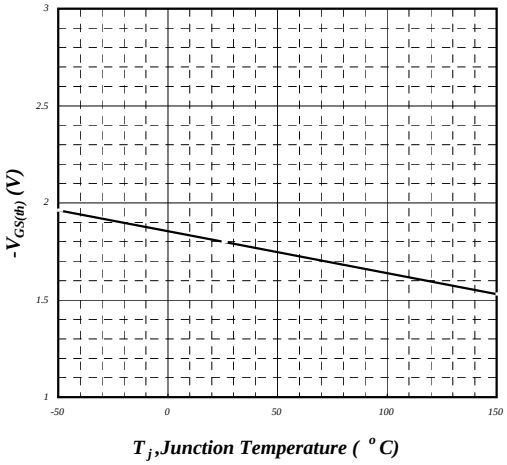
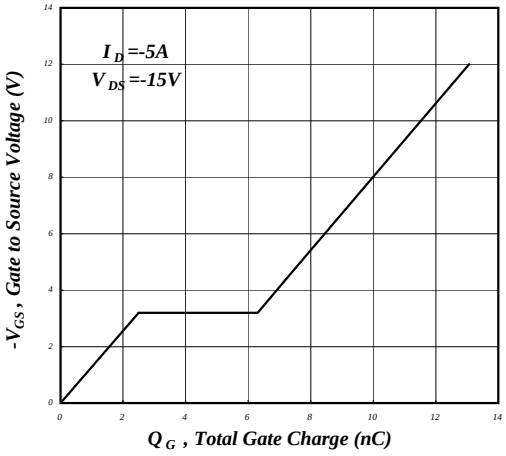


Fig 6. Gate Threshold Voltage vs. Junction Temperature

P-channel



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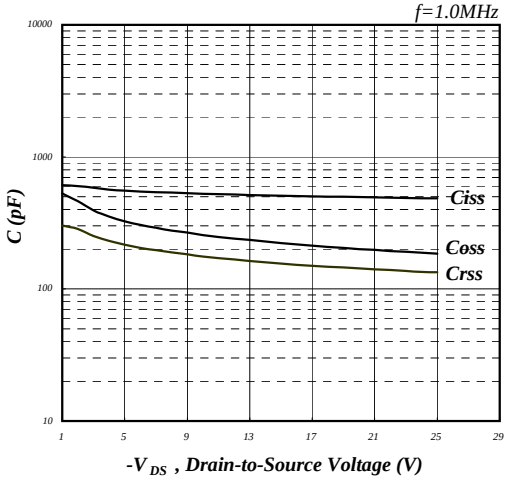

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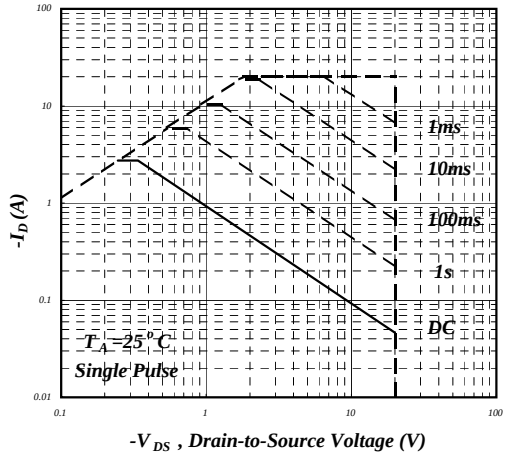

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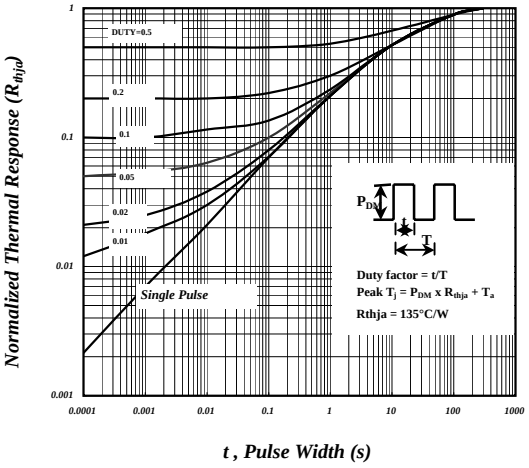

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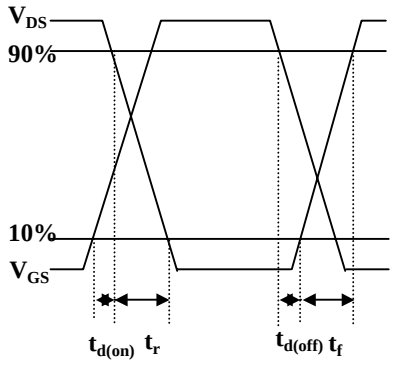

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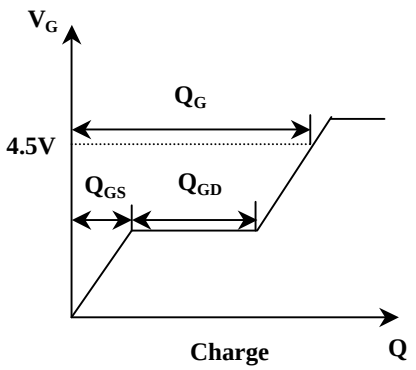

Fig 12. Gate Charge Waveform